

SEMITRANS[®] 3

IGBT4 Modules

SKM400GAL17E4

Features*

- IGBT4 = 4th generation medium fast trench IGBT (Infineon)
- CAL4 = Soft switching 4th generation CAL-Diode
- Insulated copper baseplate using DBC Technology (Direct Copper Bonding)
- With integrated Gate resistor
- For switching frequencies up to 8kHz
- UL recognized, file no. E63532

Typical Applications

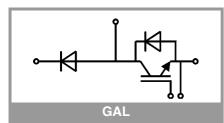
- Electronic welders
- DC/DC converter
- Brake chopper
- Switched reluctance motor

Remarks

- Case temperature limited to T_C = 125°C max.
- Recommended $T_{j,op} = -40 \dots +150^{\circ}C$
- Product reliability results valid for T_j = 150°C

Symbol	Conditions		Values	Unit	
IGBT					
V _{CES}	T _j = 25 °C		1700	V	
I _C		T _c = 25 °C	614	A	
	Τ _j = 175 °C	T _c = 80 °C	474	А	
I _{Cnom}			400	A	
I _{CRM}	_		1200	Α	
V _{GES}	_		-20 20	V	
t _{psc}	$V_{CC} = 1000 V$ $V_{GE} \le 15 V$ $V_{CES} \le 1700 V$	T _j = 150 °C	10	μs	
Tj			-40 175	°C	
Inverse d	iode			I	
V _{RRM}	T _i = 25 °C		1700	V	
l _F	T (T)	T _c = 25 °C	443	А	
	− T _j = 175 °C	T _c = 80 °C	327	Α	
I _{FRM}			800	А	
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		2340		
Tj			-40 175	°C	
Freewhee	ling diode				
V _{RRM}	T _j = 25 °C		1700	V	
l _F	T 175 00	T _c = 25 °C	443	А	
	− T _j = 175 °C	T _c = 80 °C	327	А	
I _{FRM}		-	800	A	
I _{FSM}	t _p = 10 ms, sin 18	0°, T _j = 25 °C	2340		
Tj			-40 175	°C	
Module		·			
I _{t(RMS)}			500	А	
T _{stg}	module without TIM		-40 125	°C	
V _{isol}	AC sinus 50 Hz, t = 1 min		4000	V	

Characte	ristics					
Symbol	Conditions	min.	typ.	max.	Unit	
IGBT						
V _{CE(sat)}	$I_{\rm C} = 400 {\rm A}$	T _j = 25 °C		1.92	2.20	V
	V _{GE} = 15 V chiplevel	T _j = 150 °C		2.30	2.60	V
V _{CE0}	chiplevel	T _j = 25 °C		0.80	0.90	V
		T _j = 150 °C		0.70	0.80	V
r _{CE}	V _{GE} = 15 V	T _j = 25 °C		2.8	3.3	mΩ
	chiplevel	T _j = 150 °C		4.0	4.5	mΩ
V _{GE(th)}	$V_{GE}=V_{CE}$, I_{C} = 16 mA		5.2	5.8	6.4	V
I _{CES}	$V_{GE} = 0 V, V_{CE} = 1700 V, T_j = 25 °C$				5	mA
Cies	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		32.0		nF
Coes		f = 1 MHz		1.36		nF
C _{res}		f = 1 MHz		1.16		nF
Q _G	V _{GE} = - 8 V+ 15 V			3200		nC
R _{Gint}	T _j = 25 °C			1.9		Ω





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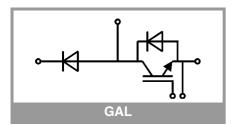
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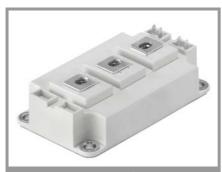
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Remarks

- Case temperature limited to T_C = 125°C max.
- Recommended $T_{j,op} = -40 \dots +150^{\circ}C$
- Product reliability results valid for T_j = 150°C

Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Unit
IGBT				••		
t _{d(on)}	V _{CC} = 1200 V	T _i = 150 °C	1	280		ns
t _r	V15/-15 V	T _i = 150 °C		45		ns
Eon	$V_{GE} = +15/-15 V$ $R_{G \text{ on}} = 2 \Omega$	T _i = 150 °C		157		mJ
t _{d(off)}	$R_{G off} = 1 \Omega$	T _i = 150 °C		760		ns
t _f	di/dt _{on} = 10000 A/	T _i = 150 °C		140		ns
E _{off}	μs di/dt _{off} = 2300 A/μs dv/dt = 5600 V/μs	T _j = 150 °C		180		mJ
R _{th(j-c)}	per IGBT	1			0.066	K/W
R _{th(c-s)}	per IGBT, P12 (refe	erence)		0.036		K/W
R _{th(c-s)}	per IGBT, HP-PCM			0.019		K/W
Inverse d	iode					
$V_F = V_{EC}$	I _F = 400 A	T _i = 25 °C		2.00	2.40	V
	V _{GE} = 0 V chiplevel	T _j = 150 °C		2.16	2.57	V
V _{F0}		T _i = 25 °C		1.32	1.56	V
	- chiplevel	T _j = 150 °C		1.08	1.22	V
r _F	chiplevel	T _j = 25 °C		1.71	2.1	mΩ
•		T _i = 150 °C		2.7	3.4	mΩ
I _{RRM}		T _j = 150 °C		615		Α
Q _{rr}	di/dt _{off} = 10100 A/	T _j = 150 °C		150		μC
E _{rr}	– μs V _{GE} = -15 V V _{CC} = 1200 V	T _j = 150 °C		130		mJ
R _{th(j-c)}	per diode	1			0.13	K/W
R _{th(c-s)}	per diode, P12 (ref	erence)		0.044		K/W
R _{th(c-s)}	per diode, HP-PCM	1		0.027		K/W
	ling diode					
$V_F = V_{EC}$	I _F = 400 A	T _j = 25 °C		2.00	2.40	V
	V _{GE} = 0 V chiplevel	T _j = 150 °C		2.16	2.57	V
V _{F0}		T _j = 25 °C		1.32	1.56	V
	- chiplevel	T _j = 150 °C		1.08	1.22	V
r _F	abialoval	T _j = 25 °C		1.71	2.1	mΩ
	- chiplevel	T _j = 150 °C	1	2.7	3.4	mΩ
I _{RRM}	$I_{\rm F} = 400 {\rm A}$	T _j = 150 °C		615		Α
Q _{rr}	_di/dt _{off} = 10100 A/ _µs	T _j = 150 °C		150		μC
E _{rr}	V _{GE} = -15 V V _{CC} = 1200 V	T _j = 150 °C		130		mJ
R _{th(j-c)}	per diode		1		0.13	K/W
R _{th(c-s)}	per diode, P12 (ref	erence)		0.044		K/W
R _{th(c-s)}	per diode, HP-PCM	1	1	0.027		K/W





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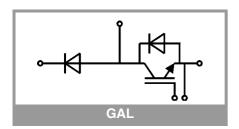
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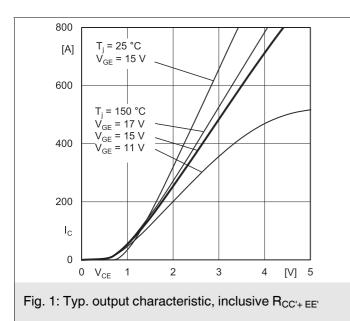
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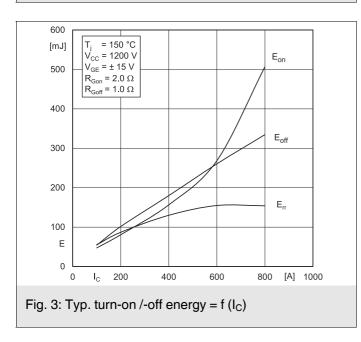
Remarks

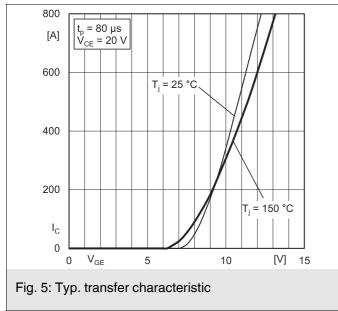
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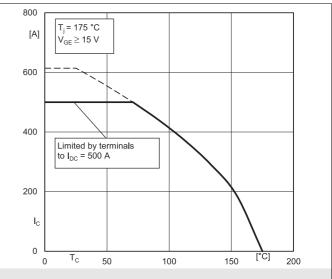
Characte	ristics					
Symbol	Conditions	min.	typ.	max.	Unit	
Module						
L _{CE}				15		nH
R _{CC'+EE'}	measured per switch	T _C = 25 °C	0.55			mΩ
		T _C = 125 °C		0.85		mΩ
R _{th(c-s)1}	calculated without thermal coupling			0.0198		K/W
R _{th(c-s)2}	including thermal coupling, T _s underneath module, P12 (reference)			0.0201		K/W
R _{th(c-s)2}	including thermal coupling, T _s underneath module, HP-PCM			0.0113		K/W
Ms	to heat sink M6		3		5	Nm
Mt		to terminals M6	2.5		5	Nm
						Nm
w		I			325	g

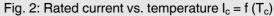


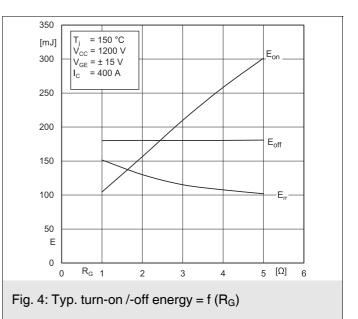


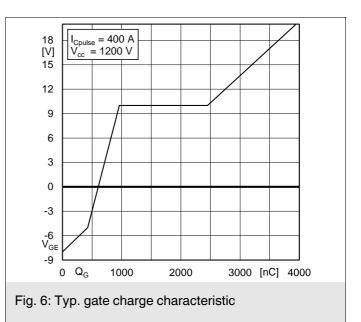


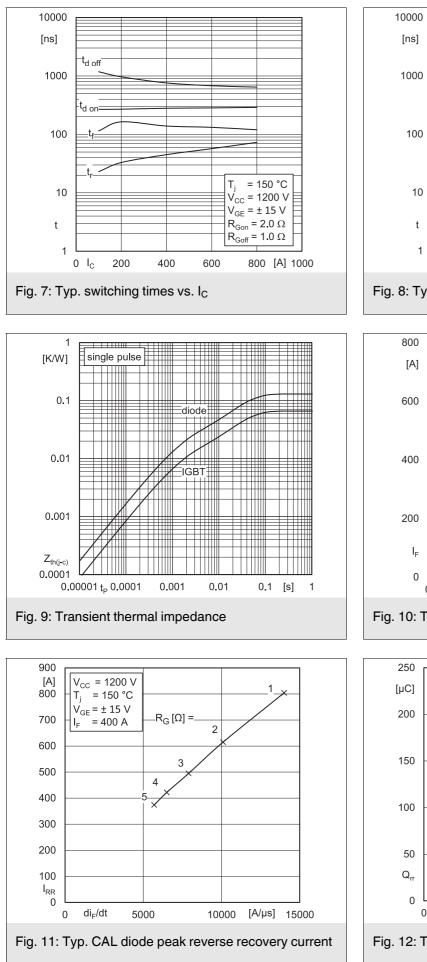


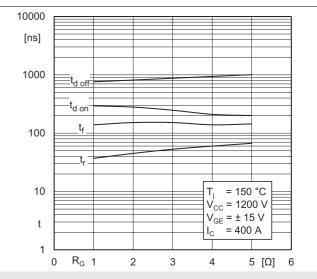


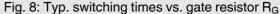


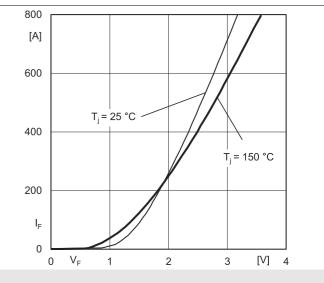


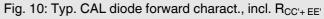


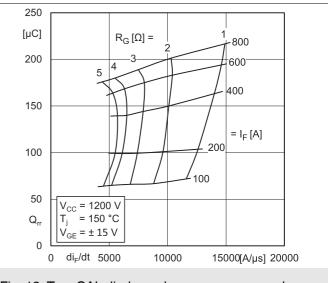


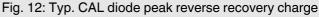


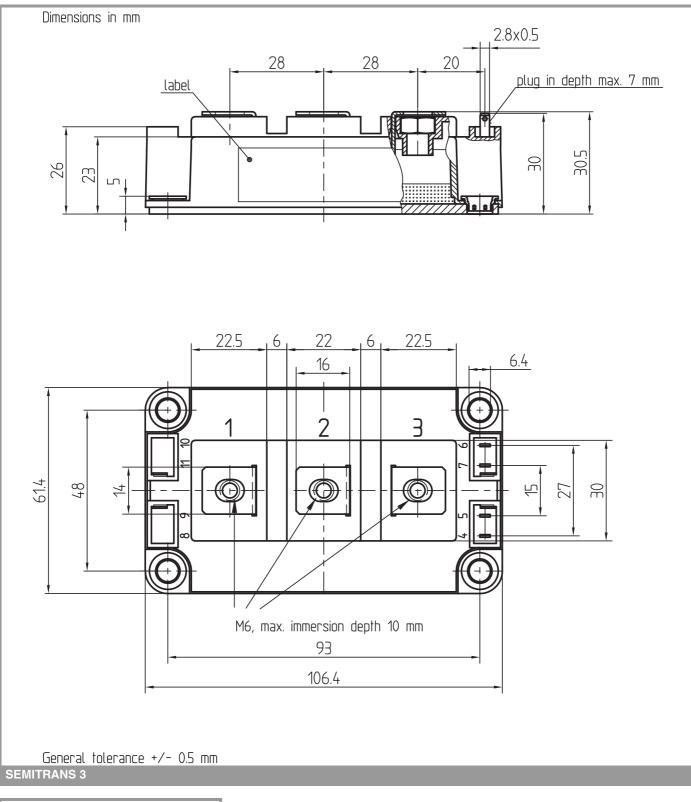


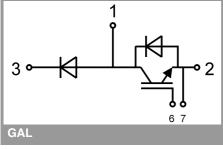












IMPORTANT INFORMATION AND WARNINGS

This is an electrostatic discharge sensitive device (ESDS) according to international standard IEC 61340.

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